



Ferrites and Accessories PQ Cores

Series/Type: PQ 20/20

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B65876E1014D001		2010-12-10	2011-03-31	2011-06-30

For further information please contact your nearest EPCOS sales office, which will also support you in selecting a suitable substitute. The addresses of our worldwide sales network are presented at www.epcos.com/sales.

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Cores B65875A series

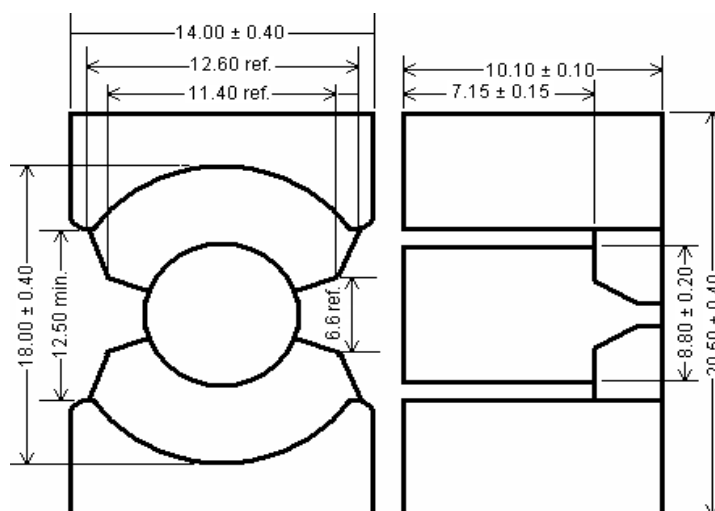
To IEC 62317-13

Delivery mode: sets

Magnetic characteristics (per set)

$\Sigma l/A$	= 0.718	mm ⁻¹
l_e	= 45.20	mm
A_e	= 62.90	mm ²
A_{min}	= 54.40	mm ²
V_e	= 2843	mm ³

Approx. weight : 15.6 g/set



Dimensions in mm

Ungapped

Material	A_L value ¹⁾ nH	μ_e	P_V W/Set	Ordering code
N87	2650 +30/-20%	1515	< 1.65 (100 kHz, 200 mT, 100 °C)	B65875A0000R087
N97	2750 +30/-20%	1565	< 1.50 (100 kHz, 200 mT, 100 °C)	B65875A0000R097
N95	3300 +30/-20%	1860	< 1.60 (100 kHz, 200 mT, 25 °C-100 °C) < 1.92 (100 kHz, 200 mT, 120 °C)	B65875A0000R095
N49	2000 +30/-20%	1150	< 0.90 (500 kHz, 50 mT, 100 °C)	B65875A0000R049

1) Measurement parameter: 10 kHz, 0.25 mT, 100 turns, room temperature.

A_L value is measured acc. to IEC62044-2. An appropriate wringing of cores with polished surface is used to improve reproducibility of the measurement. (It is recommended to rub the mating surfaces themselves six times in a circular or elliptic arc that matches the core profile before measuring A_L value).

Coil former B65876E series

Material: GFR thermosetting plastic (UL 94 V-0, insulation class to IEC 60085:

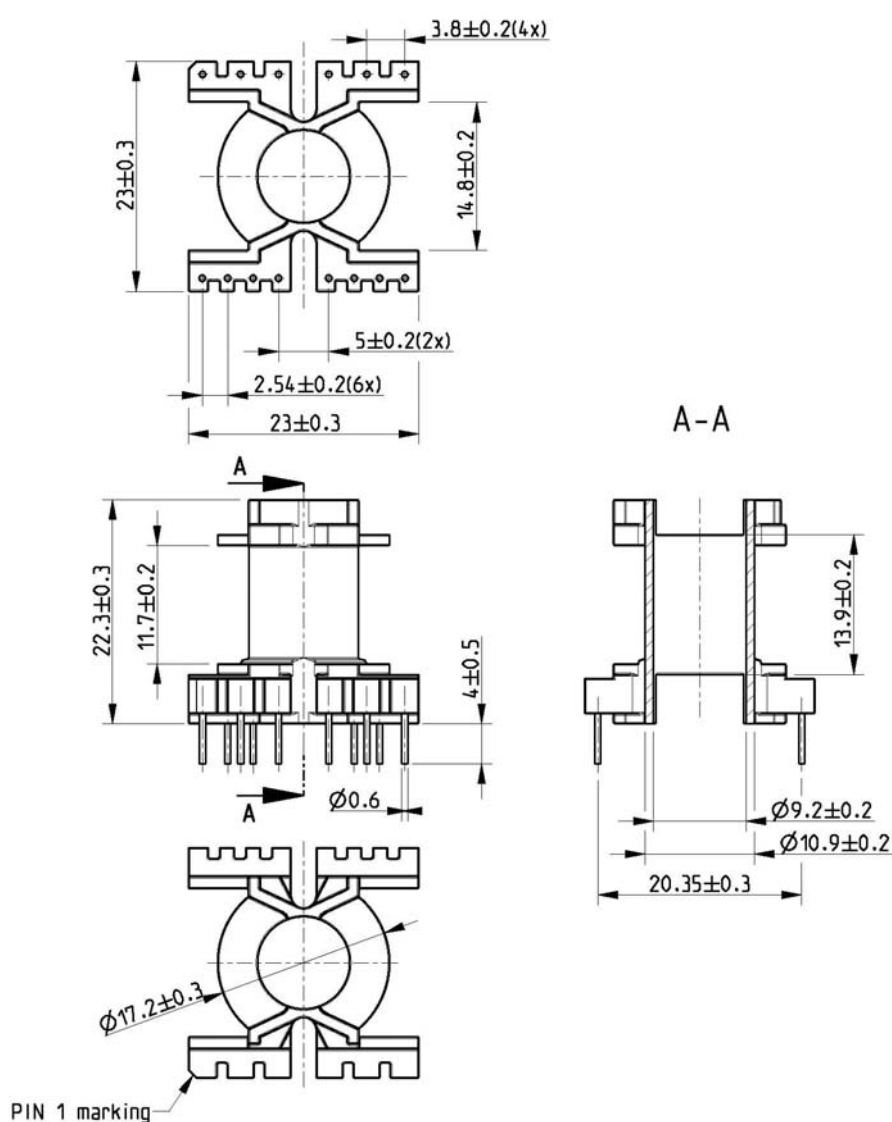
H=max.operating temperature 180 °C), color code black

Sumikon PM9820 [E41429(M)], SUMITOMO BAKELITE CO LTD

Solderability: to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s

Resistance to soldering heat: to IEC 68-2-20, test Tb, method 1B: 350 °C, 3.5 s

Sections	A _N mm ²	l _N mm	A _R value μΩ	Terminals	Ordering code
1	35	44	43	14	B65876E1014D001



Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembly and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of their special behavior under mechanical load.

Just like any ceramic material, ferrite cores are brittle and sensitive to any shock, fast changing or tensile load. Especially fast cooling rates under ultrasonic cleaning, high static and cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see Data Book 2007, chapter “General – Definitions, 8.1”.

Effects of core combination on AL value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower the value for the initial permeability. Thus, the embedding medium should offer the greatest possible elasticity.

For detailed information see Data Book 2007, chapter “General – Definitions, 8.2”.

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversibly when exposed to strong magnetic fields.

Processing notes

- The start of the winding process should be soft. Otherwise, the flanges may be destroyed.
- Excessive winding forces may damage the flanges or squeeze the tube so that the cores can no longer be mounted.
- Excessive soldering time at high temperature (>300 °C) may affect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of contamination with tin oxide (SnO) from the tin bath or burned insulation from the wire. For detailed information see Data Book 2007, chapter “Processing notes, 2.2”.
 - The dimensions of the pin hole arrangement are fixed and should be understood as an ideal recommendation for drilling the printed circuit board. In order to avoid problems when mounting the transformer, customers should make allowances for manufacturing tolerances in the drilling and pick-and-place processes by increasing the diameter of the pin holes.

Important notes

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